

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	54505	CMP	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:11
L2	150	1 and (stress strain pressure force load ) near3 (map\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:19
L3	141	2 and (sens\$4 detect\$4 transducer measur\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:12
L4	142	2 and (sens\$4 detect\$4 transducer measur\$4 gauge cell )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L5	100	4 and (wafer substrate sample specimen )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:14
L6	88	5 and (processor microprocessor CPU ECU computer )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L7	22	6 and (polish\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:13
L8	2	7 and (slurry slurries )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:14
L9	52	6 and (pad )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:14

L10	2	9 and (slurry slurries )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:13
L11	11551	(stress strain pressure force load thermal ) near3 (map\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L12	4262	11 and (wafer substrate sample specimen )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:14
L13	4262	12 and (wafer substrate sample specimen )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L14	265	13 and (slurry slurries )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L15	60	14 and (pad )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L16	29	15 and (processor microprocessor CPU ECU computer )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:15
L17	3	16 and (planarization polish\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L18	3	17 and (stress strain pressure force load )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:18
L19	584	"5647952" "5196353" "5413941" "5337015" "5308438" "5240552" "5234868"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:19

L20	0	19 and (stress strain pressure force load ) near3 (map\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L21	59	19 and (map\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L22	57	21 and (stress strain pressure force load )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L23	46	22 and (slurry slurries )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L24	46	23 and (planarization polish\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L25	46	24 and (pad )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:40
L26	46	25 and (wafer substrate sample specimen )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:20
L27	40	26 and (processor microprocessor CPU ECU computer )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:21
L28	40	27 and (sens\$4 detect\$4 transducer measur\$4 gauge cell )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:38
L29	1	28 and (eddy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:29

L30	305840	(wafer sample specimen testpiece substrate ) near3 (holder holding carrier support\$4 )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:38
L31	37445	30 and (planarization polish\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L32	26519	31 and (sens\$4 detect\$4 transducer measur\$4 gauge cell )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L33	63	32 and (stress strain pressure force load ) near3 (map\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L34	11	33 and (slurry slurries )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:39
L35	9	34 and (pad )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:40
L36	1	35 and (eddy )	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:40